

QSFP28 100GE BiDi (OM3558SX101)





Product Features

- QSFP28 MSA compliant
- IEEE 802.3 bm-2015 compliant
- 2 BiDi lanes MUX/DEMUX design
- 4 x 25.78125G electrical interface (CAUI-4)
- Maximum power consumption 4 W
- LC duplex connector
- 103.125 Gbps aggregate bit rate
- Up to 70 m/100 m transmission on OM3/OM4 fiber with FEC
- Operating case temperature: 0 to 70°C
- Single 3.3 V power supply
- I2C digital management interface
- RoHS 2 compliant

Applications

- 100GE Ethernet
- **Data Center Interconnect**
- **Enterprise Networking**



1. Description

OM3558SX101 is a QSFP28 transceiver module designed for 70/100m OM3/OM4 MM fiber optical communication applications. It is compliant with IEEE 802.3 bm-2015, QSFP28 MSA standards. Digital diagnostic management interface (DDMI) is realized by I2C interface in compliance with SFF-8636. The module is RoHS 2 compliant.

This module can convert 4-channel 25.78125 Gbps electrical data to 2-channel optical signals, and multiplex each into a BiDi (Bidirectional) 53.125 Gbps optical transmission. Similarly, it optically demultiplexes from Bidi 53.125 Gbps optical signals, and converts them to 4-channel output electrical data on the receiver side. It has been designed to meet the harshest external operating conditions including temperature, humidity and EMI interference.

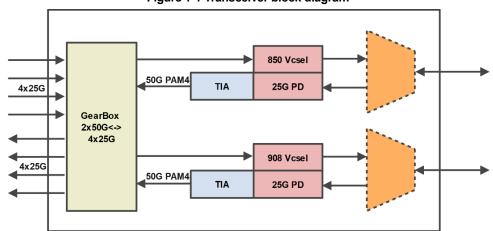


Figure 1-1 Transceiver block diagram

2. Pin Descriptions

38 **GND** GND 37 Tx2n 2 Tx1n 36 Tx1p Tx2p 3 Module 35 GND GND 4 34 Tx3n Tx4n 5 33 Тх3р Тх4р 6 32 GND **GND** 7 Card 31 LPMode ModSeIL 8 30 Vcc1 ResetL 9 l Edge VccRx 29 VccTx 28 SCL IntL 11 27 ModPrsL SDA 12 26 GND **GND** 13 25 Rx4p Rx3p 14 24 Rx4n Rx3n 15 23 GND GND 16 22 Rx2p Rx1p 17 21 Rx1n 18 Rx2n GND 20 GND 19 Top Side Viewed **Bottom Side Viewed**

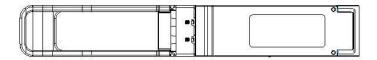
Figure 2-1 MSA compliant connector

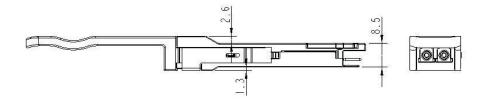
from Top

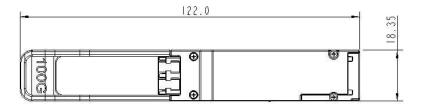
from Bottom

3. Mechanical Specifications

Figure 3-1 Mechanical dimensions







4. Ordering Information

Part number	Description
OM3558SX101	QSFP28 100G BiDi

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